

KOH Etching System

Features

The molten KOH etching is a useful method for revealing the etch pits of SiC wafer or GaN wafer.

This system is capable of KOH etching process safely and automatically.



Specifications

MODEL	ETC-2001F	ETC-6001F
Crucible size	ϕ 100×H90(t2)	ϕ 200×H149(t2)
Wafer size	1×2" ϕ	1×6" ϕ
Maximum heating temperature	700°C	
Temp. control stability	±1°C	
Wafer holder lift	auto	
Wafer holder rotation	max 10rpm	
Crucible shutter	manual	
Power Supply	1 ϕ 200V 15A	1 ϕ 200V 20A
Exhaust port diameter	ϕ 100	
System size	W750×D650×H1650	
System weight	180kg	190kg
Option	Differential pressure gauge, Signal tower	